

Media release

Cicor opens 3D-MID technology centre in Boudry (Switzerland)

Zurich, 4 March 2011. Cicor Group (SIX Swiss Exchange: C1CN; based in Boudry, Switzerland) – a leading internationally active provider of printed circuit boards, microelectronics and electronic manufacturing services – is forging ahead with 3D-MID technology and opening a competence centre in Boudry. This centre concentrates on the development and client-specific application of 3D-MID products and ensures that the associated manufacturing know-how is spread to all Cicor companies around the world. The group is taking this step to stay ahead of the trend towards miniaturization and rationalization in the electronics industry.

3D-MID (moulded interconnect devices) technology facilitates the integration of mechanical and electronic functions within a very small component. The electronic circuit is integrated into the casing, making it possible to achieve much more compact construction and much greater function density. More and more applications involving electrical and electro-optical circuits are made using 3D-MID technology. Use of moulded interconnect devices can drastically reduce process stages, assembly times and the number of separate components required. The main areas of application are in the automotive, medical technology, industrial technology and telecommunications sectors.

Cicor has many years of experience with these types of application. Equally important, it has the expertise to advise its customers on whether their technical challenges can best be resolved through the use of a flexible or rigid-flexible PCB on the one hand, or 3D-MID technology on the other. In addition, Cicor Group offers all the process steps for manufacturing products using 3D-MID technology – from injection moulding to laser structuring and metallization, to set-up and interconnect technology, to assembly – and all from a single source.

The potential size of the market for 3D-MID is comparable to that of the PCB and sensor markets. After intensive research and development efforts that began in the 1980s, 3D-MID technology entered a rapid growth phase two years ago. Its progress has been fuelled by the development of numerous materials and stable manufacturing processes specially suited to 3D-MID.



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About Cicor • Cicor is a Swiss group of leading companies in the electronics industry. It is organized into four divisions: Printed Circuit Boards (PCB), Microelectronics (ME), Electronic Solutions (ES) and Asia. The group's companies provide complete outsourcing services and a broad range of technologies for the manufacture of highly complex PCBs, hybrids and electronic modules. With around 1200 employees in 11 production sites in Switzerland and abroad, the group supplies high-quality custom-made solutions to its clients in Europe, America and Asia. The shares of Cicor Technologies Ltd. are listed on the SWX Swiss Exchange (CICN). For further information please visit www.cicor.com.